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09/814,255	03/21/2001	Shunpei Yamazaki	07977-107002	5578
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			2811	
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

PATDOCTC@fr.com

Office Action Summary	Application No. 09/814,255	Applicant(s) YAMAZAKI ET AL.	
	Examiner Ori Nadav	Art Unit 2811	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 23 July 2009.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 20,28,31,33-35,38,40-42,45,47-50,53 and 55-60 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 20,28,31,33-35,38,40-42,45,47-50,53 and 55-60 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date <u>7/23/09</u> . | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 41-42, 45, 47, 49-50, 53, 55 and 59-60 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

The claimed limitation of “the source electrode is in contact with the semiconductor layer through a contact hole that is opened in the interlayer insulating film and the gate insulating film, and that is directly over the source region”, as recited in claims 41 and 49, is unclear as to which element is formed directly over the source region.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 20, 28, 31, 34-35, 38 and 57-58 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hollinger (5,089,434) in view of Kudoh (5,159,416) and Tanaka et al. (5,798,744).

Regarding claims 20 and 34, Hollinger teaches in figures 1 and 13D and related text a semiconductor device having a transistor the transistor comprising:

- a semiconductor layer 20 including a source region 24;

- a gate insulating film 26, 62 on and in contact with the semiconductor layer, the gate insulating film defining a first contact hole extending from a first opening located at a top surface of the gate insulating film to a second opening located at a bottom surface of the gate insulating film, and the semiconductor layer defining a recess having a third opening located in a top surface of the source region that is in communication with the second opening, the third opening defining an area that is greater than an area defined by the second opening such that a portion of the gate insulating film extends directly over a portion of the recess;

- an anodic oxide film (top part of layer 62) on the gate electrode;

- a second insulating film (the other one of 26, 62) on and in contact with the anodic oxide film, the second insulating film defining a second contact hole extending from a fourth opening located at a top surface of the second insulating film to a fifth opening located at a bottom surface of the second insulating film, and the anodic oxide film defining a second recess having a sixth opening located at a top surface of the anodic oxide film that is in communication with the fifth opening, the sixth opening

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defining an area that is greater than an area defined by the fifth opening such that a portion of the second insulating film extends over a portion of the second recess;

a gate electrode 12a on the gate insulating film; and

a source electrode 16 in contact with the semiconductor layer through the contact hole,

wherein the source electrode contains a first layer 16, and

wherein the recess is filled with the first layer, and

wherein the first layer is in contact with the gate insulating film.

Note that the gate insulating film comprises layers 26 and the bottom part of 62, because layers 26 and 62 comprise silicon oxide and are thus indistinguishable from each other.

Although Hollinger forms the gate insulating film as layers 26 and the bottom part of 62, these are process limitations which would not carry patentable weight in this claim drawn to a structure, because distinct structure is not necessarily produced.

Note that a “product by process” claim is directed to the product per se, no matter how actually made, *In re Hirao*, 190 USPQ 15 at 17 (footnote 3). See also *In re Brown*, 173 USPQ 685; *In re Luck*, 177 USPQ 523; *In re Fessmann*, 180 USPQ 324; *In re Avery*, 186 USPQ 161; *In re Wertheim*, 191 USPQ 90 (209 USPQ 554 does not deal with this issue); and *In re Marosi et al.*, 218 USPQ 289, all of which make it clear that it is the patentability of the final product per se which must be determined in a “product by process” claim, and not the patentability of the process, and that an old or obvious product produced by a new method is not patentable as a product, whether claimed in

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product by process claims or not. Note that the applicant has the burden of proof in such cases, as the above case law makes clear.

Hollinger does not teach using the device as a thin film transistor, such that the semiconductor layer is on an insulating surface, an interlayer insulating film, a source electrode contains a second layer, and wherein the first layer is an alloy of aluminum and an element belonging to one of groups 12 to 15, and wherein the element belonging to one of groups 12 to 15 is at least one selected from the group consisting of germanium, tin, gallium, zinc, lead, indium, and antimony.

That is, Hollinger does not teach using the device as a thin film transistor, such that the semiconductor layer is on an insulating surface, an interlayer insulating film, a source electrode contains a second layer, and a first layer is an alloy of aluminum and germanium.

Kudoh teaches in figure 9 and related text using the device as a thin film transistor, such that the semiconductor layer is on an insulating surface, an interlayer insulating film and a source electrode contains a second layer.

Tanaka et al. teach a first layer can be germanium compound (column 9, lines 56-61).

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use Hollinger's device as a thin film transistor, such that the semiconductor layer is on an insulating surface, to use an interlayer insulating film and a source electrode contains a second layer, in order to use the device in an application

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which requires TFT, to provide better protection to the device, and in order to operate the device by providing external connections to the device, respectively.

Furthermore, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a first layer comprises germanium compound in Hollinger's device, in order to improve the device characteristics.

Note that forming a first layer comprises germanium, as taught by Tanaka et al., and a second layer of aluminum, as taught by Kudoh means that the first layer would comprise aluminum-germanium, because the aluminum would react with the germanium.

Note that substitution of materials is not patentable even when the substitution is new and useful. *Safetran Systems Corp. v. Federal Sign & Signal Corp.* (DC NIII, 1981) 215 USPQ 979.

Regarding claims 28 and 35, prior art's device includes a semiconductor layer contains crystalline silicon, and a silicon oxide interlayer insulating film.

Regarding claims 31 and 38, prior art's device includes a second layer contains aluminum.

Regarding claims 57-58, prior art's device includes a first layer flowable at less than 450 degrees Celsius, because the material of the first layer in prior art's device is identical to that of the claimed invention.

Claims 33 and 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hollinger, Kudoh and Tanaka et al., as applied to the claims above, and further in view of Applicant Admitted Prior Art (AAPA).

Regarding claims 33 and 40, Hollinger, Kudoh and Tanaka et al., teach substantially the entire claimed structure, as applied to claims 20, 34 above, except using the device as an active matrix type EL display device.

AAPA teaches using thin film device as an active matrix type EL display device.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use prior art's device as an active matrix type EL display device, in order to use the device in an application which requires an active matrix type EL display device.

Claims 41-42, 45, 47, 49-50, 53, 55 and 59-60, as best understood, are rejected under 35 U.S.C. 103(a) as being unpatentable over Hollinger, Kudoh and Tanaka et al., as applied to the claims above, and further in view of Miyakawa (5,278,449).

Regarding claims 41 and 49, Hollinger, Kudoh and Tanaka et al., teach substantially the entire claimed structure, as applied to claims 20, 34 above, except a part of the second and fourth layers located directly over the interlayer insulating film.

That is, Hollinger, Kudoh and Tanaka et al. do not teach forming the first layer as a lamination of two sub-layers, such that part of the second and fourth layers are located directly over the interlayer insulating film.

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Miyakawa teaches in figure 7 and related text forming the first layer as a lamination of two sub-layers Ti/TiN, wherein the second sub-layer is used as a barrier layer.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a barrier layer in prior art's device by forming the first layer as a lamination of two sub-layers, such that part of the second and fourth layers are located directly over the interlayer insulating film, in order to improve the device characteristics by using barrier layers, as is well known in the art.

Regarding claims 42, 47, 50 and 55, prior art's device includes a semiconductor layer contains crystalline silicon, and a silicon oxide interlayer insulating film.

Regarding claims 45 and 53, prior art's device includes a second layer contains aluminum.

Claims 48 and 56 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hollinger, Kudoh and Tanaka et al. and Miyakawa, as applied to the claims above, and further in view of Applicant Admitted Prior Art (AAPA).

Regarding claims 48 and 56, Hollinger, Kudoh and Tanaka et al. and Miyakawa teach substantially the entire claimed structure, as applied to claims 41 and 49 above, except using the device as an active matrix type EL display device.

AAPA teaches using thin film device as an active matrix type EL display device.

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It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use prior art's device as an active matrix type EL display device, in order to use the device in an application which requires an active matrix type EL display device.

Response to Arguments

Applicant argues that Hollinger does not teach the claimed limitations of “the semiconductor layer defining a recess having a third opening located in a top surface of the source region that is in communication with the second opening, the third opening defining an area that is greater than an area defined by the second opening such that a portion of the gate insulating film extends directly over a portion of the recess”, because, “the trench 60 does not have a third opening located in a top surface of the N+ doped region 24 that has an area greater than an area defined by the opening between the two spacers 62 that is located at the bottom surface of the spacers 62. Rather, while Hollinger appears to show in Figs. 15 and 16 that the N+ doped region 24 has an opening located in its top surface at the location of overhang 64, this opening has a much smaller area than that of the opening located between the two spacers 62 located at the bottom surface of the spacers 62”.

Hollinger teaches in figure 13D a semiconductor layer defining a recess having a third opening located in a top surface of the semiconductor layer. Although figures 15 and 16 are not very clear as to the exact location of source region 24, source region 24

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is formed by doping both edges of the semiconductor layer on opposite sides of the opening. Since the original trench opening is not filled with semiconductor material, said opening in the semiconductor layer (or in the source region) defines an area that is greater than an area defined by the second opening, as claimed.

Note that the broad recitation of the claim does not require the source region to be located directly below the third opening. Clearly, Hollinger does not teach the unclaimed limitations of “a recess having a third opening located in a top surface of the source region, wherein at least a part of the source region is located directly below the third opening.

Applicant argues that prior art does not teach the claimed limitation of “the source electrode is in contact with the semiconductor layer through a contact hole that is opened in the interlayer insulating film and the gate insulating film, and that is directly over the source region”, as recited in claims 41 and 49, because “Each of claims 41 and 49 has also been amended to recite that the contact hole is directly over the source region”.

Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993). Applicant does not claim that the contact hole is directly over the source region, because the claimed limitation of “the source electrode is in contact with the semiconductor layer through a contact hole that is opened in the interlayer insulating film and the gate insulating film, and that is directly over the source

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region”, is not synonymous to the limitation of “the contact hole is directly over the source region”.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ori Nadav whose telephone number is 571-272-1660. The examiner can normally be reached between the hours of 7 AM to 4 PM (Eastern Standard Time) Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lynne Gurley can be reached on 571-272-1670. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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